

TITLE OF THE INVENTION

SEMICONDUCTOR DEVICE

CROSS-REFERENCE TO RELATED APPLICATIONS

This application is based upon and claims the
5 benefit of priority from the prior Japanese Patent
Application No. 2002-239732, filed August 20, 2002,
the entire contents of which are incorporated herein
by reference.

BACKGROUND OF THE INVENTION

10 1. Field of the Invention

The present invention relates to a wiring layout
to weaken an electric field generated between the lines
exposed to a high voltage, particularly to the bit
lines of a nonvolatile semiconductor memory.

15 2. Description of the Related Art

First of all, the prior art of the present
invention will be explained taking a NAND flash memory,
a kind of nonvolatile semiconductor memory, as
an example.

20 FIG. 1 shows an example of a cell array of a NAND
flash memory. In this example, only one NAND block
(erase unit) is shown to simplify the explanation.

A NAND flash memory is a kind of electrically
rewritable nonvolatile semiconductor memory. A NAND
25 block represents an erase unit, and all the data in the
memory cell of a NAND block is erased simultaneously.
A NAND block has a plurality of NAND cell units 1.

These NAND cell units 1 are placed in a cell's P-well area, CPWELL, for example.

A NAND cell unit comprises a NAND string comprising a plurality of memory cells 2 connected in series, one select gate transistor 3 connected to one end of the NAND series, and another select gate transistor 3 connected to another end of the NAND series. The one select gate transistor 3 connected to the one end of the NAND series is connected to a common source line CELSRC, and the another select gate transistor 3 connected to the another end of the NAND series is connected to bit lines BL_{1e} - BL_{ne} and BL_{1o} - BL_{no}.

Word lines WL 0, WL 1 to WL 15 are connected to the memory cells 2 in the NAND cell unit, and they function as control gate electrodes of the memory cells 2. Select gate lines SGS and SGD are connected to the select gate transistors 3 in the NAND cell unit 1, and they function as gate electrodes of the select gate transistors 3.

In this example, a sense amplifier (S/A) 4 employs a cell array structure with two bit lines BL_{ie} and BL_{io} (i = 1, 2, to n) connected through a select circuit 5A. Two bit lines BL_{ie} and BL_{io} are connected to a shielded power line BLSHIELD through a select circuit 5B. With this structure, a so-called shielded bit line reading method can be used upon reading operation.

Namely, since the N-channel MOS transistor 6A turns on when the control signal BLSe is "H" and the control signal BLSo is "L", the even-numbered bit line BLie is electrically connected to the sense amplifier

5 4. As the control signal BIASe becomes "L" and the control signal BIASo becomes "H" at this time, the N-channel MOS transistor 7B is ON and the shielding potential VSHIELD (e.g., 0V) is supplied to the odd-numbered bit line BLio.

10 Further, since the N-channel MOS transistor 7A turns on when the control signal BLSe is "L" and the control signal BLSo is "H", the odd-numbered bit line BLio is electrically connected to the sense amplifier
4. As the control signal BIASe becomes "H" and the
15 control signal BIASo becomes "L" at this time, the N-channel MOS transistor 6B is ON and the shielding potential VSHIELD (e.g., 0V) is supplied to the even-numbered bit line BLie.

It is noted here that the even and odd numbers are
20 determined by the bit line numbers counted from left to right assuming the leftmost bit line to be 0.

Since all bit lines BL1e, ... BLne; BL1o, ... BLno become high potential (erase potential) upon erasing, the N-channel MOS transistors 6A, 6B and 7A, 7B in the
25 select circuits 5A and 5B, respectively, consist of high voltage MOS transistors.

In a NAND flash memory, during writing and

erasing, electric charge is injected into/ejected from the floating gate electrode by an FN tunnel current.

During the writing operation, 20V is applied to the selected word line WLj and 0V is applied to the
5 cell's P-well area (the memory cell channel) CPWELL, for example.

During the erasing operation, 0V is applied to the word line WL0, WL1 to WL15 in the selected NAND block, and 20V is applied to the cell's P-well area (channel
10 of memory cell) CPWELL, for example.

When erasing, all bit lines BL1e - BLne and BL1o - BLno are actually floating.

However, when 20V is applied to the cell's P-well area CPWELL, a forward bias diode (cell's P-well area +
15 N-type diffusion layer) is connected between the cell's P-well area CPWELL and the bit lines BL1e - BLne and BL1o - BLno. As a result, the bit lines BL1e - BLne and BL1o - BLno are also charged to about 20V.

As described above, during writing or erasing, the
20 selected word line WLj or all the bit lines BL1e - BLne and BL1o - BLno are charged to about 20V. Therefore, as a potential difference between these lines and other lines increases, a dielectric breakdown occurs between these lines, and a line short-circuit problem arises.

25 Particularly, in recent years, the cell array has become finer and the wiring design rule has become narrower. This increases the possibility of

short-circuit due to an intense electric field in and in the proximity of a cell array.

Hereinafter, the problem will be discussed in detail taking bit lines of a nonvolatile semiconductor memory, as an example.

FIG. 2 shows a wiring layout of the part indicated as the area B in FIG. 1. FIG. 3 shows an equivalent circuit diagram of the layout of FIG. 2.

The bit lines BL1e, BL1o, BL2e, BL2o are arranged as metal lines M1 with minimum width and minimum space in a memory chip.

The above-mentioned minimum width means the minimum width determined by the processing technique of lithography. The minimum space means the minimum space S1 which is influenced by the lithography technique, but in principle makes no short-circuit in the lines due to dielectric breakdown when a voltage (potential difference) V1 is generated between the lines.

The bit lines BL1e and BL2e are connected to the N-type drain diffusion layer of the N-channel MOS transistor 6B through the V1 contact plug, metal line M0 and CS contact plug. The bit lines BL1o and BL2o are connected to the N-type drain diffusion layer of the N-channel MOS transistor 7B through the V1 contact plug, metal line M0 and CS contact plug.

The shielded power line BLSHIELD is connected to the N-type source diffusion layers of N-channel MOS

transistors 6B and 7B through a V1 contact plug,
a metal line M0 and a CS contact plug.

The metal line M0 means the lines in the lowest
layer which are directly connected to a silicon
5 substrate (e.g., a N-type diffusion layer) Si using
a CS contact plug without passing through other metal
lines. The metal line M1 means the lines in one layer
above M0.

The gate electrodes of the N-channel MOS
10 transistors 6B and 7B are made of conductive
polysilicon film containing impurities, for example.

In the wiring layout of this example, since the
bit lines BL1e, BL1o, BL2e, BL2o are arranged with
minimum width and minimum space, a fringe is not given
15 to the bit lines BL1e, BL1o, BL2e, BL2o in the contact
area (above the V1 contact plug). Further, the size of
the V1 contact plug is larger than the width of the bit
lines BL1e, BL1o, BL2e, BL2o.

Therefore, the space between the bit lines BL1e,
20 BL1o, BL2e, BL2o and the V1 contact plug becomes
smaller than the minimum space where no dielectric
breakdown occurs between the lines.

Specifically, in the example shown in FIGS. 2 and
3, the space between the bit line BL1o and the V1
25 contact plug in the area X1 becomes smaller than the
minimum space. The space between the shielded power
line BLSHIELD and the V1 contact plug in the area X2 is

also reduced to be smaller than the minimum space.

As a result, an electric field concentrates on these reduced areas, and a dielectric breakdown occurs, spoiling the reliability of the nonvolatile
5 semiconductor memory.

Further, in the wiring layout of this example, the bit lines BL1e, BL1o, BL2e, BL2o are arranged with minimum width and minimum space, and the space between the shielded power supply BLSHIELD and the bit lines
10 BL1e, BL1o, BL2e, BL2o is set to be minimum.

However, it is to be noted that this minimum space is determined by the voltage V1 impressed across the bit lines BL1e, BL1o, BL2e, BL2o. Namely, a voltage larger than V1 may be applied to between the shielded
15 power line BLSHIELD and the bit lines BL1e, BL1o, BL2e, BL2o.

In this case, a line short-circuit occurs due to concentration of electric field between the shielded power line BLSHIELD and the bit lines BL1e, BL1o, BL2e, BL2o, failing to ensure the reliability of the
20 nonvolatile semiconductor memory.

FIG. 4 shows signal waveforms upon erasing.

At the time t1 to t3, 20V is applied as an erasing voltage to the cell's P-well area CPWELL. The bit
25 lines BL1e, BL1o, BL2e, BL2o are charged to about 20V, specifically 20V-Vf. (Vf is the forward bias voltage between the cell's P-well area and N-type diffusion

layer.) The shielded power line BLSHIELD is charged to Vcc (approx. 3V, for example).

Therefore, during the erase operation, a potential difference of $20V - V_{cc}$ occurs between the bit line BL1o and the shielded power line BLSHIELD in FIG. 2, for example.

Particularly, in the areas X1 and X2, the space between the bit line BL1o and the shielded power line BLSHIELD is narrower than the minimum space. Further, considering contact holes, line shifts or uneven shapes occurred during the lithography, the space between the bit line BL1o and the shielded power line BLSHIELD may be reduced further.

Therefore, there is a very large possibility of line short-circuit due to concentration of electric field on the area between the shielded power line BLSHIELD and the bit lines BL1e, BL1o, BL2e, BL2o.

A short-circuit in a line causes leakage of the electric charge on erasing from the cell's P-well area to the bit line BL1o, for example and further to the shielded power line BLSHIELD, failing to supply the cell's P-well area with the voltage large enough to do the erase operation.

This will result in defective erasing, lowering the reliability of the nonvolatile semiconductor memory.

As explained above, as the design rule becomes

very small with the finer element, the possibility of a short-circuit between the lines exposed to high voltage increases. This has been the problem in the prior art.

BRIEF SUMMARY OF THE INVENTION

5 A semiconductor device according to a first aspect of the present invention comprises first and second lines arranged with a first interval, and third and fourth lines arranged with a second interval wider than the first interval; wherein the first interval is
10 a minimum interval less than $0.12\ \mu\text{m}$, and a maximum value of a voltage generated between the third and fourth lines is greater than a maximum value of a voltage generated the first and second lines.

 A semiconductor device according to a second
15 aspect of the present invention comprises first and second lines in a wiring layer arranged with a first interval, a third line arranged in the wiring layer, wherein a second interval between the first and third lines is wider than the first interval, and a first
20 transistor configured to connect the second and third lines; wherein the first interval is a minimum interval less than $0.12\ \mu\text{m}$, and a maximum value of a voltage generated between the first and third lines is greater than a maximum value of a voltage generated between
25 the first and second lines.

 A semiconductor device according to a third aspect of the present invention comprises first and second

lines in a wiring layer arranged with a first interval,
a third line arranged in the wiring layer, and a first
transistor configured to connect the second and third
lines; wherein the first interval is a minimum interval
5 less than $0.12\ \mu\text{m}$, and a maximum value of a voltage
generated between the first and third lines is greater
than a maximum value of a voltage generated the first
and second lines, and the third line is arranged at
a position not adjacent to the first line.

10 BRIEF DESCRIPTION OF THE SEVERAL VIEWS OF THE DRAWING

FIG. 1 is a circuit diagram of a cell array of
a NAND flash memory;

FIG. 2 is a plane view of a conventional wiring
layout;

15 FIG. 3 is a circuit diagram substituting for
the layout of FIG. 2;

FIG. 4 shows waveforms indicating the timing of
erase operation;

20 FIG. 5 is a view showing a first concept of
the present invention;

FIG. 6 is a view showing a second concept of
the present invention;

FIG. 7 is a view showing a third concept of
the present invention;

25 FIG. 8 is a plane view showing a wiring layout
according to a first embodiment of the present
invention;

FIG. 9 is a circuit diagram substituting for the layout of FIG. 8;

FIG. 10 is a plane view showing a wiring layout according to a second embodiment of the present invention;

FIG. 11 is a circuit diagram substituting for the layout of FIG. 10; and

FIG. 12 is a plane view showing a wiring layout according to a third embodiment of the present invention.

DETAILED DESCRIPTION OF THE INVENTION

Description will be given on a semiconductor device according to an aspect of the present invention hereinafter with reference to the accompanying drawings.

1. Concept

(1) Concept 1

FIG. 5 is a view showing a first concept of the present invention.

It is assumed that first and second lines are formed on the same wiring layer, and a potential difference of V_1 maximum is applied across these two lines. A space S_1 between the first and second lines is set to a value that will not make a short-circuit in a line due to dielectric breakdown when at least the potential difference V_1 is applied across the first and second lines.

This value may be a minimum value that will not make a short-circuit in a line due to dielectric breakdown when a potential difference V_1 is applied across the first and second lines, or it may be a value
5 in accordance with the lithography technique.

Here, the minimum value is assumed to be equivalent to the minimum dimension limited by the lithography technique or the design rule (the value lower than $0.12\ \mu\text{m}$). Namely, the space S_1 is defined
10 as a minimum value that will not make a line short-circuit due to dielectric breakdown when the potential difference V_1 is applied across the first and second lines.

On the other hand, third and fourth lines are
15 assumed to be formed on the same wiring layer, and a potential difference of V_2 maximum ($>V_1$) is assumed to be applied across the third and fourth lines. The third and fourth lines may be formed on the same wiring layer as that of the first and second lines, or
20 they may be formed on a different wiring layer.

In this case, the space S_2 between the third and fourth lines is set larger than the space S_1 , specifically the value that will not make a line short-circuit due to dielectric breakdown when at least
25 the potential difference V_2 is applied across the third and fourth lines. More specifically, the space S_2 is set to the minimum value or larger that will not make

a line short-circuit due to dielectric breakdown when the potential difference V2 is applied across the third and fourth lines.

(2) Concept 2

5 FIG. 6 is a view showing a second concept of the present invention.

It is assumed that first and second lines are formed on the same wiring layer, and a potential difference of V1 maximum is applied across these two
10 lines. A space between the first and second lines is set to the design rule (the value lower than $0.12\ \mu\text{m}$, for example) or the minimum value capable of being processed by lithography.

It is also assumed that the size of a contact plug
15 is larger than the width of the second line. In this case, a space Sa between the first line and the contact plug is narrower than the space between the first and second lines (the design rule or the minimum processing value).

20 The space Sa between the first line and the contact plug is set to a value that will not make a line short-circuit due to dielectric breakdown when at least the potential difference V1 is applied across the first and second lines. Specifically, the space Sa is
25 set to the minimum value that will not make a line short-circuit due to dielectric breakdown when the potential difference V1 is applied across the first and

second lines.

On the other hand, third and fourth lines are assumed to be formed on the same wiring layer, and a potential difference of V_2 maximum ($>V_1$) is assumed to be applied across these two lines. The third and fourth lines may be formed on the same wiring layer as that of the first and second lines, or they may be formed a different wiring layer.

In this case, a space S_b between the third line and the contact plug is set larger than the space S_a , or the value that will not make a line short-circuit due to dielectric breakdown when a potential difference V_2 is applied across the third and fourth lines. More specifically, the space S_b is set to the minimum value or larger that will not make a line short-circuit due to dielectric breakdown when the potential difference V_2 is applied across the third and fourth lines.

(3) Concept 3

FIG. 7 is a view showing a third concept of the present invention.

It is assumed that first and second lines are formed on the same wiring layer, and a potential difference of V_1 maximum is applied across these two lines. A space S_1 between the first and second lines is set to a value that will not make a line short-circuit when a potential difference of at least V_1 is applied across the first and second lines. This value

is equivalent to the design rule (the value lower than $0.12\text{ }\mu\text{m}$, for example) or the minimum value capable of being processed by lithography.

On the other hand, a third line is assumed to be
5 formed on the same wiring layer as that of the first
and second layers, and a potential difference of V_2
maximum ($>V_1$) is assumed to be applied across the first
and third lines. In this case, a space S_2 between the
first and third line is set larger than the space S_1 ,
10 specifically, the minimum value or larger that will not
make a line short-circuit due to dielectric breakdown
when at least the potential difference V_2 is applied
across the first and third lines.

It is to be noted that the second and third lines
15 are connected by a high voltage MOS transistor.

(4) Numerical value example

The concept 1 relates to a wiring layout to
determine the space S_2 between the third and fourth
lines, when the space S_1 between the first and second
20 lines has been determined. The concept 3 relates to
the layout to determine the space S_2 between the first
and third lines, when the space S_1 between the first
and second lines was already determined.

In the concepts 1 and 3, the expression E
25 (Electric field) = $V_1/S_1 = V_2/S_2$ is established between
the spaces S_1 and S_2 .

The concept 2 relates to a wiring layout to

determine the space S_b between the third line and the contact plug, when the space S_a between the first line and the contact plug was already determined.

In the concept 2, the expression E (Electric field) = $V_1/S_a = V_2/S_b$ is established between the spaces S_1 and S_2 .

The values of S_1 , S_2 , S_a and S_b can be simulated based on the above expressions.

For example, if V_1 is fixed to 3.6V and V_2 is fixed to 20V, S_2 becomes 0.56 μm when S_1 is 0.1 μm . If S_1 is 0.09 μm , S_2 becomes 0.50 μm . If S_1 is 0.05 μm , S_2 becomes 0.28 μm . If S_1 is 0.03 μm , S_2 becomes 0.167 μm . If S_1 is 0.025 μm , S_2 becomes 0.14 μm .

It is to be noted that these numerical values S_1 , S_2 , S_a and S_b actually mean the wiring spaces after completion of wiring and processing. During wiring and processing, unexpected conditions such as shifts in aligning a mask may occur. Namely, there will be a certain transformation difference between the design wiring intervals (the sizes when making a layout pattern) S_1' , S_2' , S_a' , S_b' before the wiring/processing, and the actual intervals after the wiring/processing.

Therefore, the design wiring intervals S_1' , S_2' , S_a' , S_b' shall be determined by taking account of the transformation difference.

(5) Summary

As explained above, the space S1 or Sb that is to be the narrowest space, or the value of the space S2 or Sb between the third and fourth lines or between the first and third lines, is determined based on the maximum potential differences V1 and V2 generated between the first and second lines and between the third and fourth lines.

The space value determined as above facilitates the layout of the third and fourth lines or the first and third lines to which a high voltage V2 is applied, and thereby ensures reliability of a semiconductor device in operation with a high voltage.

2. Embodiments

Hereinafter, details of preferable embodiments of the present invention will be explained.

(1) Embodiment 1

FIG. 8 is a plane view showing a wiring layout according to a first embodiment of the present invention. FIG. 9 is a circuit diagram substituting for the layout of FIG. 8.

The layout of FIG. 8 corresponds to the part B in FIG. 1, and is a modification of the conventional layout of FIG. 2.

Each of the N-channel MOS transistors 6B and 7B, as a select circuit, has the function of selecting a bit line to apply a shielding potential VSHIELD, and

at the same time, it has the function of preventing transmission of the potential (approx. 20V) of the bit lines BL1e, BL1o, BL2e, BL2o to the shielded power line BLSHIELD, upon erase operation.

5 It is very difficult to prevent the transmission of the charge from the cell's P-well area CPWELL to the bit lines BL1e, BL1o, BL2e, BL2o, during the erase operation. On the other hand, the shielded power line BLSHIELD is charged to about a power supply potential
10 Vcc (e.g., 3V) during the erase operation.

 Therefore, it is necessary to separate the shielded power line BLSHIELD (including the V1 contact plug) sufficiently from the bit lines BL1e, BL1o, BL2e, BL2o (including the V1 contact plug) formed on the same
15 wiring layer, to weaken the electric field generated therebetween. It is preferable not to adjacent the shielded power line BLSHIELD to the bit lines BL1e, BL1o, BL2e, BL2o in the width direction of the wiring.

 For this purpose, this embodiment fully utilizes
20 a metal line M0 laid just under the shielded power line BLSHIELD, and a metal line M1 as bit line BL1e, BL1o, BL2e, BL2o.

 As seen from FIG. 1, all the select circuits 5B (N-channel MOS transistors 6B and 7B) of the shielded
25 power line BLSHIELD side are commonly connected to the shielded power line BLSHIELD.

 Thus, in this embodiment, the sources of the

N-channel MOS transistors 6B and 7B in a plurality of
(e.g., two) select circuits 5B are commonly connected
by a metal line M0, and this metal line M0 is extended
up to the area where none of bit lines BL1e, BL1o,
5 BL2e, BL2o exists. And, in this area, the metal line
M0 is connected to the shielded power line BLSHIELD
(the metal line M1) by the V1 contact plug.

This realizes the wiring layout where the shielded
power line BLSHIELD (including the V1 contact plug) is
10 not adjacent, in the wiring width direction, to the bit
lines BL1e, BL1o, BL2e, BL2o (including the V1 contact
plug) formed on the same wiring layer.

Therefore, the shielded power line BLSHIELDL can be
formed sufficiently isolated from the bit lines BL1e,
15 BL1o, BL2e, BL2o on the same wiring layer, thereby
ensuring the reliability of a semiconductor device in
high-voltage operation.

It is also necessary for prevention of a line
short-circuit due to dielectric breakdown to take
20 sufficient space between the metal line M0 provided as
an intermediate layer to connect the N-channel MOS
transistors 6B, 7B to the bit lines BL1e, BL1o, BL2e,
BL2o, and the metal line M0 provided as an intermediate
layer to connect the shielded power line BLSHIELD to
25 the N-channel MOS transistors 6B, 7B.

(2) Embodiment 2

FIG. 10 is a plane view showing a wiring layout

according to a second embodiment of the present invention. FIG. 11 is an equivalent circuit diagram of the layout of FIG. 10.

5 The layout of FIG. 10 corresponds to the part A in FIG. 1.

Each of the N-channel MOS transistors 6A and 7A, as a select circuit, has the function of selecting a bit line to be connected to the sense amplifier S/A, and at the same time, it has the function of preventing
10 transmission of the potential (approx. 20V) of the bit lines BL1e, BL1o, BL2e, BL2o to the sense amplifier S/A, upon erase operation.

It is very difficult to prevent the transmission of the charge from the cell's P-well area CPWELL to the
15 bit lines BL1e, BL1o, BL2e, BL2o, during the erase operation. On the other hand, the gate potentials BLS2 and BLSO of the N-channel MOS transistors 6A and 7A, as a select circuit, are set to a power supply potential V_{cc} (e.g., 3V), and the potentials of the bit lines BL1
20 and BL2 before branching of the sense amplifier S/A side is set to about $V_{cc}-V_t$ (V_t is the threshold voltage of MOS transistor), upon erase operation.

Therefore, it is necessary to separate the bit lines BL1 and BL2 (including the V1 contact plug)
25 sufficiently from the bit lines BL1e, BL1o, BL2e, BL2o (including the V1 contact plug) formed on the same wiring layer, to weaken the electric field generated

therebetween. For this purpose, this embodiment fully utilizes a metal line M0 laid just under the bit lines BL1 and BL2, and a metal line M1 as bit lines BL1e, BL1o, BL2e, BL2o.

5 As seen from FIG. 1, concerning the wiring layout of the bit lines BL1 and BL2, unlike the wiring layout of the shielded power line BLSHIELD, the select circuits 5A (N-channel MOS transistors 6A and 7A) must be independently connected to the sense amplifier
10 S/A. Thus, in this embodiment 2, the sources of the N-channel MOS transistors 6A and 7A in a plurality of select circuits 5A cannot be commonly connected by a metal line M0.

 Thus, in this embodiment, the metal lines M0
15 connected to the N-channel MOS transistors 6A and 7A are extended for each select circuit 5A up to the area where the bit lines BL1e, BL1o, BL2e, BL2o are coarsely arranged metal lines M1. And, in this area, the metal lines M0 are connected to the bit lines BL1 and BL2
20 (the metal lines M1) by the V1 contact plug.

 It is more desirable that metal line M0 can be extended up to the area where none of bit lines BL1e, BL1o, BL2e, BL2o exists.

 This realizes the wiring layout where the bit
25 lines BL1 and BL2 before branching (including the V1 contact plug) are not adjacent in the wiring width direction to the bit lines BL1e, BL1o, BL2e, BL2o

(including the V1 contact plug) formed on the same wiring layer.

Even if the bit lines BL1 and BL2 before branching are adjacent in the wiring width to the bit lines BL1e, BL1o, BL2e, BL2o, a sufficiently wide space is taken
5 therebetween compared to the space between the bit lines BL1e, BL1o, BL2e, BL2o, as indicated by the area X4 in FIGS. 10 and 11.

Therefore, the bit lines BL1 and BL2 before
10 branching (including the V1 contact plug) can be formed sufficiently isolated from the bit lines BL1e, BL1o, BL2e, BL2o on the same wiring layer, whereby the electric field between the lines can be weakened and the reliability of a semiconductor device can be
15 ensured in high-voltage operation.

Further, since the bit lines BL1 and BL2 before branching and the bit lines BL1e, BL1o, BL2e, BL2o will not be shorted due to dielectric breakdown, a high voltage will not be applied to the MOS transistors in
20 the sense amplifier S/A, and the gate or junction of the MOS transistors will not be broken.

It is also necessary for prevention of a line short-circuit due to dielectric breakdown to take sufficient space between the metal line M0 provided as
25 an intermediate layer to connect the N-channel MOS transistors 6B, 7B to the bit lines BL1e, BL1o, BL2e, BL2o, and the metal line M0 provided as an intermediate

layer to connect the bit lines BL1 and BL2 before
branching to the N-channel MOS transistors 6A, 7A.

(3) Embodiment 3

FIG. 12 is a plane view showing a wiring layout
5 according to a third embodiment of the present
invention.

This wiring layout is a modification of the wiring
layout of FIG. 8.

In the embodiment of FIG. 8, a wiring layer M0 is
10 used to realize the layout where the shielded power
line BLSHIELD is sufficiently separated from the bit
lines BL1e, BL1o, BL2e, BL2o formed on the same wiring
layer M1, to weaken the electric field therebetween.
This achieves the objects of the present invention,
15 eliminating an extremely narrow space between the lines
and preventing a short-circuit due to dielectric
breakdown between the lines.

However, in the embodiment of FIG. 8, the
coarseness of the wiring pattern increases in the
20 areas where the wiring width and space between lines
are narrow. Thus, this layout is not optimum for
lithography and processing of the wiring layer M1.

In this embodiment, a dummy pattern (a dummy line)
DUMMY is laid in an empty space around the bit lines
25 BL1e, BL1o, BL2e, BL2o formed on the wiring layer M1.

The space between the dummy pattern DUMMY and
the bit lines BL1e, BL1o, BL2e, BL2o may be the same as

the space between the bit lines BL1e, BL1o, BL2e, BL2o, or may be wider than that space.

5 The dummy pattern DUMMY put in an empty space around the bit lines BL1e, BL1o, BL2e, BL2o provides a good result in the lithography and processing of the wiring layer M1.

10 In the embodiment of FIG. 12, two dummy patterns DUMMY are made in the empty space around the bit lines BL1e, BL1o, BL2e, BL2o. These dummy patterns DUMMY are being floated, and not given a potential.

As described above, this embodiment achieves the primary object of the present invention to weaken the electric field generated between lines, and realizes a wiring layout with excellent processing accuracy.

15 3. Others

Although the present invention has been explained, taking an example of a NAND flash memory, the invention is applicable to other types of nonvolatile semiconductor memory.

20 Bit lines exposed to a high voltage are used in the embodiments of the invention, but the other lines such as word lines and ordinary lines can be used.

Moreover, the invention is applicable to semiconductor memories other than a nonvolatile memory, to the other types of semiconductor circuit, such as a logic LSI.

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4. Effects

As explained hereinbefore, a semiconductor device according to an aspect of the present invention realizes a new wiring layout to weaken an electric field between the lines exposed to a high voltage, and ensures the reliability of a semiconductor in operation with a high voltage.

Additional advantages and modifications will readily occur to those skilled in the art. Therefore, the invention in its broader aspects is not limited to the specific details and representative embodiments shown and described herein. Accordingly, various modifications may be made without departing from the spirit or scope of the general inventive concept as defined by the appended claims and their equivalents.